AMENDMENTS TO THE SPECIFICATION

Please amend paragraph 0015, beginning at page 4, as follows:

Description of the Preferred Embodiments

[0015] Referring to FIG. 1, an electronic package 10 is generally illustrated having a surface mount electronic device 22 mounted onto the surface of a circuit board ~~14~~ 12. While only a portion of the electronic package 10 is shown and described herein, it should be appreciated that the electronic package 10 may include any number of one or more surface mount devices 22 mounted onto circuit board 12 and connected to circuit board 12 by way of a controlled height solder joint interconnection according to the present invention.

Please amend paragraph 0017, beginning at page 5, as follows:

[0017] Formed on the upper surface 20 of circuit board 12 are electrically conductive mounting pads 28 which serve to mechanically and electrically connect the surface mount electronic device 22 to circuit board 12. The ~~mounting pads 28~~ circuit board 12 may be connected to electrical circuitry 16 to provide an electrical circuit path. The circuit board 12 may include a solder resist layer (not shown) printed on the upper surface of each of mounting pads 28 to define a solder window boundary that contains the volume of reflowed solder. During a solder reflow process, the solder paste is reshaped on the upper surface of the mounting pad 28.

Please amend paragraph 0027, beginning at page 8, as follows:

[0027] Accordingly, the solder joint 30 ~~interconnect~~ interconnection achieved with the present invention advantageously provides for an enhanced electrical and mechanical connection which may achieve a reduction in strain energy of the solder

joint 30 by providing additional columnar solder height. Additionally, the controlled height solder interconnection allows for a reduction in component count, enhanced efficiency in use of the circuit board 12, simplified assembly and processing, and a reduction in the number of component placement machines that may be required for the electronic package 10.